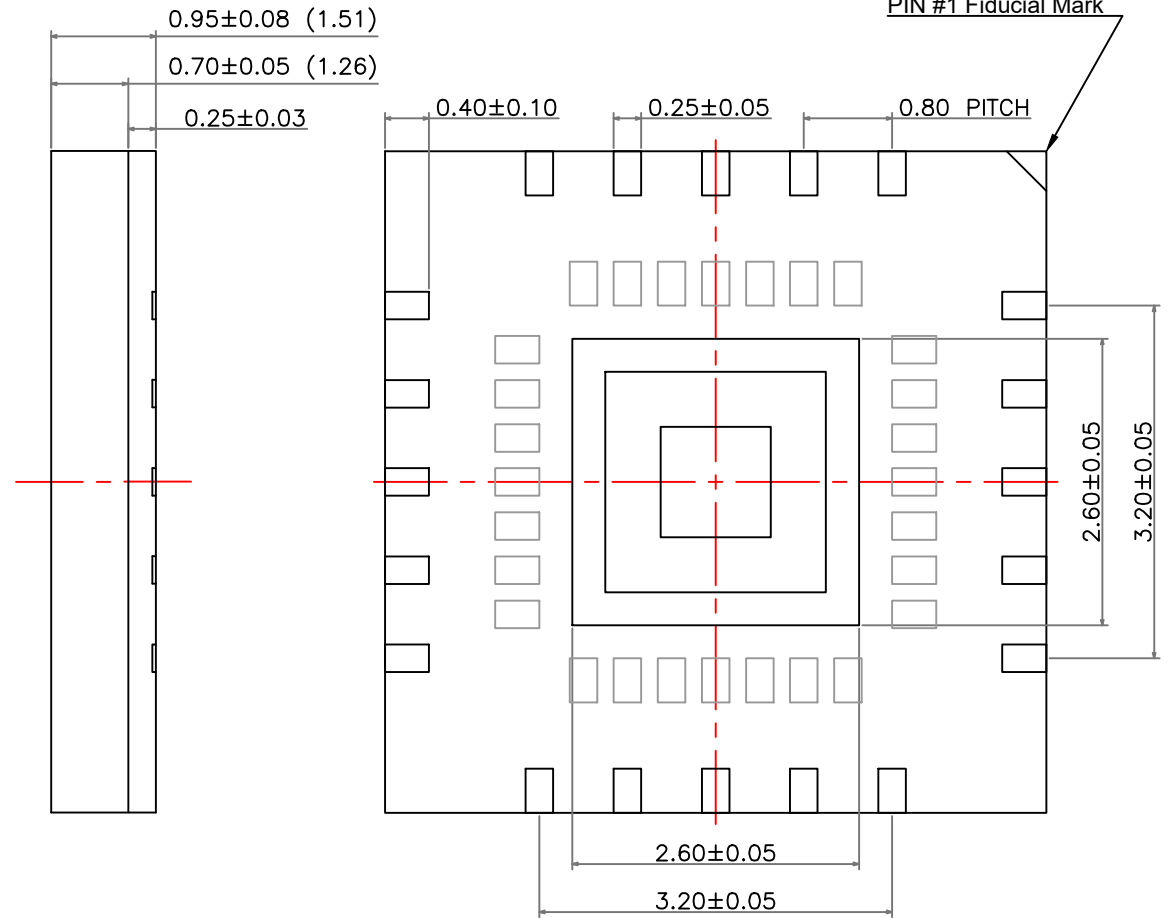


TOP VIEW



SIDE VIEW

BOTTOM VIEW

NOTES :

1. DRAWING CONFORM TO JEDEC
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. SOLDERABLE EXPOSED PAD : 2.60 X 2.60 MM
4. DIMENSIONING AND TOLERANCING PER JEDEC
5. DIVERSIFICATION OF THE PKG OUTLINE IS POSSIBLE AS A LAND RADIAL TYPE

| DESIGNED BY | CHECKED BY | CHECK BY | APPROVED BY | TITLE | | |
|--|------------|----------|-------------|---|-----------|--------|
| K.S.YUN | | | | PKG OUTLINE DIMENSION MLQFN 20LD 6x6mm | | |
| 10/01/2023 | | | | UNIT | TOLERANCE | SCALE |
| SNPT (Semiconductor And Packaging Testing Corporation) | | | | MM | - | 1:1 |
| | | | | DWG NO. | SPEC NO. | SHEET |
| | | | | POD-MLQFN-0620 | MLQFN-08 | 1 OF 1 |